

L Number	Hits	Search Text	DB	Time stamp
17	2850	(solid near state) and (heat\$4 WITH adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 08:53
24	229	((solid near state) and (heat\$4 WITH adhesive)) and cross near linked	USPAT	2003/07/25 08:53
25	13	(solid near state with plate) and (heat\$4 WITH adhesive) and cross near linked	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 08:56
32	1	(solid near state) and (heat\$4 WITH adhesive with (cross near linked)) and (optical\$5 near2 pump\$4) and active	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 08:58
46	4	(solid near state) and (heat\$4 WITH adhesive with (cross near linked))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:03
52	4	(solid near state) and (heat\$4 WITH adhesive with (cross near linked)) and ((heat neat sink) or cool\$5)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:06
39	5	(solid near state) and (heat\$4 WITH adhesive with (cross near linked))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:22
58	2	(solid near state) and (adhesive with (cross near linked)) and active and (heat near sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:26
65	12	(solid near state) and (adhesive with (cross near linked)) and (heat near sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:40
72	0	(solid near state) and (adhesive near (layer or film or region or medium) with (cross near linked)) and (heat near sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:36
79	29	(solid near state) and (adhesive near (layer or film or region or medium) with (cross near linked))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:48
86	0	(solid near state) and (adhesive with (cross near linked)) SAME (heat near sink)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:48
92	0	(solid near state) and (adhesive near (layer or film or region or medium) with (cross near linked)) and (optical\$5 near pump\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:50

99	289	(solid near state) and (optical\$5 near pump\$4) and (heat near sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 09:52
107	0	((solid near state) and (optical\$5 near pump\$4) and (heat near sink)) and (adhesive near (layer or film or region or medium) with (cross near linked))	USPAT	2003/07/25 09:54
108	0	((solid near state) and (optical\$5 near pump\$4) and (heat near sink)) and (adhesive with (cross near linked))	USPAT	2003/07/25 09:54
106	238	(solid near state) and (optical\$5 near pump\$4) and (heat near sink)	USPAT	2003/07/25 10:01
109	209	((solid near state) and (optical\$5 near pump\$4) and (heat near sink)) and 372/\$.ccls.	USPAT	2003/07/25 09:59
110	190	(solid near state near laser) and (optical\$5 near pump\$4) and (heat near sink) and 372/\$.ccls.	USPAT	2003/07/25 10:21
111	81	(solid near state near laser) and (optical\$5 near pump\$4) and (heat near sink) and 372/\$.ccls. and amplif\$5	USPAT	2003/07/25 10:23
-	1002	(solid near state) and active and amplif\$5 and cool\$4 and thermal\$5 and heat\$4 and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/02 16:54
-	391	(solid near state) and active and (laser with amplif\$5) and cool\$4 and thermal\$5 and heat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/02 16:59
-	251	((solid near state) and active and (laser with amplif\$5) and cool\$4 and thermal\$5 and heat\$4 ) and 372/\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/02 17:01
-	259	(solid near state near laser) and active and (laser with amplif\$5) and cool\$4 and thermal\$5 and heat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/02 17:01
-	199	((solid near state near laser) and active and (laser with amplif\$5) and cool\$4 and thermal\$5 and heat\$4 ) and 372/\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:00
-	154	((solid near state near laser) and active and (laser with amplif\$5) and cool\$4 and thermal\$5 and heat\$4 ) and liquid and solid and material	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:03
-	244	((solid near state) and active and (laser with amplif\$5) and cool\$4 and thermal\$5 and heat\$4 ) and liquid and solid and material	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:29
-	162	((solid near state) and active and (laser with amplif\$5) and cool\$4 and thermal\$5 and heat\$4 ) and liquid and solid and material) and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:24

-	47	((solid near state) and active and (laser with amplif\$5) and cool\$4 and thermal\$5 same heat\$4 ) and (liquid with solid same material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:35
-	55	((solid near state) and active and (laser with amplif\$5) and cool\$4 and thermal\$5 and heat\$4 ) and (liquid with solid same material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:40
-	113	(solid near state) and semiconductor and active and laser and amplif\$5 and cool\$4 and thermal\$5 and heat\$4 and (liquid same solid same material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 10:44
-	84	((solid near state) and semiconductor and active and laser and amplif\$5 and cool\$4 and thermal\$5 and heat\$4 and (liquid same solid same material)) and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:17
-	1	((solid near state with plate) and semiconductor and active and laser and amplif\$5 and cool\$4 and thermal\$5 and heat\$4 and (liquid same solid same material)) and volum\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:23
-	8	((solid near state) with plate) and semiconductor and active and laser and amplif\$5 and cool\$4 and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:26
-	20	((solid near state) with plate) and semiconductor and active and laser and amplif\$5 and cool\$4 and thermal\$5 and heat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:33
-	20	((solid near state) SAME plate) and semiconductor and active and laser and amplif\$5 and cool\$4 and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:36
-	1	((solid near state) with (body or member or system)) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif\$5) and (cool\$4 near2 (body or member or system)) and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:45
-	2	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif\$5) and (cool\$4 near2 (body or member or system)) and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:50
-	1	((solid near state) with (body or member or system)) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif\$5) and (cool\$4 near2 (body or member or system)) and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:54

-	1	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif\$5) and cool\$5 and (thermal\$5 near2 (body or member or system)) and heat\$4 and (liquid AND solid AND material)) and volum\$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 15:58
-	0	((solid near state) with (body or member or system)) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif\$5) and cool\$5 and (thermal\$5 near2 (body or member or system)) and heat\$4 and (liquid AND solid AND material)) and volum\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:02
-	1	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif\$5) and cool\$5 and (thermal\$5 near2 (body or member or system)) and heat\$4 and (liquid AND solid AND material)) and volum\$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:06
-	95	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif\$5) and (cool\$5) and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:18
-	2	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser with amplif\$5) and (cool\$5 near2 (body or member or system)) and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:18
-	8	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif\$5) and (cool\$5 near2 (body or member or system)) and thermal\$5 and heat\$4 and (liquid AND solid AND material)) and volum\$5 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:18
-	22	(solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif\$5) and (cool\$5 near2 (body or member or system)) and heat\$4 and plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:27
-	20	(solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif\$5) and (cool\$5 near2 (body or member or system)) and heat\$4 and plate and thermal\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:46
-	15	((solid near state) and semiconductor and (active near (layer or region or medium or film)) and (laser AND amplif\$5) and (cool\$5 near2 (body or member or system)) and heat\$4 and plate and thermal\$5) and (mirror or reflect\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 16:40
-	40	(solid near state) and (active near (layer or region or medium or film)) and laser and (cool\$5 near2 (body or member or system)) and heat\$4 and plate and thermal\$5 and (mirror or reflect\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/03 17:06
-	8	((solid near state) and (active near (layer or region or medium or film)) and laser and (cool\$5 near2 (body or member or system)) and heat\$4 and plate and thermal\$5 and (mirror or reflect\$5)) and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/25 08:49